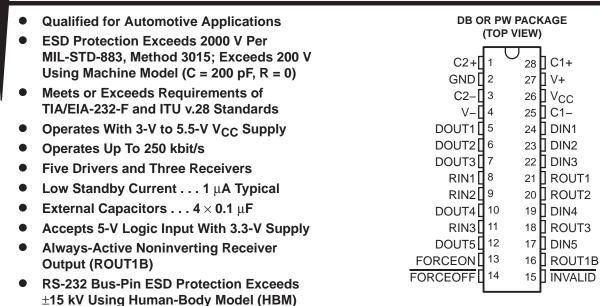
# MAX3238-Q1 3-V TO 5.5-V MULTICHANNEL RS-232 LINE DRIVER/RECEIVER WITH ±15-kV ESD (HBM) PROTECTION SLLS569B - MAY 2003 - REVISED APRIL 2008



## description/ordering information

The MAX3238 consists of five line drivers, three line receivers, and a dual charge-pump circuit with ±15-kV ESD (HBM) protection pin to pin (serial-port connection pins, including GND). The device meets the requirements of TIA/EIA-232-F and provides the electrical interface between notebook and subnotebook computer applications. The charge pump and four small external capacitors allow operation from a single 3-V to 5.5-V supply. In addition, the device includes an always-active noninverting output (ROUT1B), which allows applications using the ring indicator to transmit data while the device is powered down. These devices operate at data signaling rates up to 250 kbit/s and a maximum of 30-V/µs driver output slew rate.

#### ORDERING INFORMATION<sup>†</sup>

TA	PACKAGE‡		ORDERABLE PART NUMBER	TOP-SIDE MARKING
SSOP (DB) Ta		Tape and reel	MAX3238IDBRQ1	MAX3238Q
-40°C to 85°C	TSSOP (PW)	Tape and reel	MAX3238IPWRQ1	MB3238Q

<sup>†</sup> For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at http://www.ti.com.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



<sup>‡</sup>Package drawings, thermal data, and symbolization are available http://www.ti.com/packaging.

# 3-V TO 5.5-V MULTICHANNEL RS-232 LINE DRIVER/RECEIVER WITH ±15-kV ESD (HBM) PROTECTION SLLS569B - MAY 2003 - REVISED APRIL 2008

## description/ordering information (continued)

Flexible control options for power management are featured when the serial port and driver inputs are inactive. The auto-powerdown plus feature functions when FORCEON is low and FORCEOFF is high. During this mode of operation, if the device does not sense valid signal transitions on all receiver and driver inputs for approximately 30 s, the built-in charge pump and drivers are powered down, reducing the supply current to 1 μA. By disconnecting the serial port or placing the peripheral drivers off, auto-powerdown plus occurs if there is no activity in the logic levels for the driver inputs. Auto-powerdown plus can be disabled when FORCEON and FORCEOFF are high. With auto-powerdown plus enabled, the device automatically activates once a valid signal is applied to any receiver or driver input. INVALID is high (valid data) if any receiver input voltage is greater than 2.7 V or less than -2.7 V, or has been between -0.3 V and 0.3 V for less than 30 µs. INVALID is low (invalid data) if all receiver input voltages are between -0.3 V and 0.3 V for more than 30 µs. Refer to Figure 5 for receiver input levels.

#### **Function Tables**

#### **EACH DRIVER**

		INF	PUTS	OUTPUT	
DIN	FORCEON	FORCEOFF	TIME ELAPSED SINCE LAST RIN OR DIN TRANSITION	DOUT	DRIVER STATUS
Х	Χ	L	X	Z	Powered off
L	Н	Н	X	Н	Normal operation with
Н	Н	Н	X	L	auto-powerdown plus disabled
L	L	Н	<30 s	Н	Normal operation with
Н	L	Н	<30 s	L	auto-powerdown plus enabled
L	L	Н	>30 s	Z	Powered off by auto-powerdown
Н	L	Н	>30 s	Z	plus feature

H = high level, L = low level, X = irrelevant, Z = high impedance

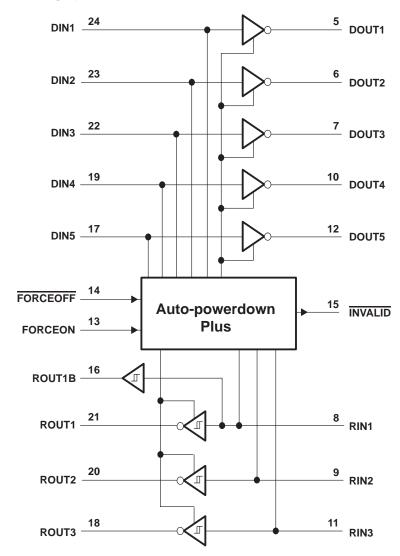
#### **EACH RECEIVER**

		INF	PUTS	OUTP	UTS	
RIN1	RIN2-RIN3	FORCEOFF	TIME ELAPSED SINCE LAST RIN OR DIN TRANSITION	ROUT1B	ROUT	RECEIVER STATUS
L	Χ	L	X	L	Z	Powered off while
Н	Χ	L	X	Н	Z	ROUT1B is active
L	L	Н	<30 s	L	Н	
L	Н	Н	<30 s	L	L	Normal operation with
Н	L	Н	<30 s	Н	Н	auto-powerdown plus
Н	Н	Н	<30 s	Н	L	disabled/enabled
Open	Open	Н	>30 s	L	Н	

H = high level, L = low level, X = irrelevant, Z = high impedance (off), Open = input disconnected or connected driver off



# logic diagram (positive logic)



# MAX3238-Q1

# 3-V TO 5.5-V MULTICHANNEL RS-232 LINE DRIVER/RECEIVER WITH ±15-kV ESD (HBM) PROTECTION SLLS569B - MAY 2003 - REVISED APRIL 2008

## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage range, V <sub>CC</sub> (see Note 1)	0.3 V to 6 V
Positive output supply voltage range, V+ (see Note 1)	0.3 V to 7 V
Negative output supply voltage range, V- (see Note 1)	0.3 V to –7 V
Supply voltage difference, V+ – V– (see Note 1)	13 V
Input voltage range, V <sub>I</sub> : Driver (FORCEOFF, FORCEON)	
Receiver	
Output voltage range, V <sub>O</sub> : Driver	13.2 V to 13.2 V
Receiver (INVALID)	$-0.3 \text{ V to V}_{CC} + 0.3 \text{ V}$
Package thermal impedance, θ <sub>JA</sub> (see Notes 2 and 3): DB package	62°C/W
PW package	62°C/W
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	260°C
Storage temperature range, T <sub>stg</sub>	–65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. All voltages are with respect to network GND.
  - 2. Maximum power dissipation is a function of  $T_J(max)$ ,  $\theta_{JA}$ , and  $T_A$ . The maximum allowable power dissipation at any allowable ambient temperature is  $P_D = (T_J(max) - T_A)/\theta_{JA}$ . Operating at the absolute maximum  $T_J$  of 150°C can affect reliability.
  - 3. The package thermal impedance is calculated in accordance with JESD 51-7.

## recommended operating conditions (see Note 4 and Figure 6)

					NOM	MAX	UNIT
	Cumplicustana		$V_{CC} = 3.3 \text{ V}$	3	3.3	3.6	\/
	Supply voltage		V <sub>CC</sub> = 5 V	4.5	5	5.5	V
V	V <sub>IH</sub> Driver and control high-level input voltage	DIN FORCES FORCES	V <sub>CC</sub> = 3.3 V	2			V
VIH		DIN, FORCEOFF, FORCEON	V <sub>C</sub> C = 5 V	2.4			V
VIL	Driver and control low-level input voltage	DIN, FORCEOFF, FORCEON				8.0	V
٧ı	Driver and control input voltage	DIN, FORCEOFF, FORCEON		0		5.5	V
٧ı	Receiver input voltage			-25		25	V
T <sub>A</sub>	Operating free-air temperature		MAX3238I	-40		85	°C

NOTE 4: Testing supply conditions are C1–C4 = 0.1  $\mu$ F at V<sub>CC</sub> = 3.3 V  $\pm$  0.15 V; C1–C4 = 0.22  $\mu$ F at V<sub>CC</sub> = 3.3 V  $\pm$  0.3 V; and C1 = 0.047  $\mu$ F and C2–C4 = 0.33  $\mu F$  at V  $_{CC}$  = 5 V  $\pm$  0.5 V.

## electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 4 and Figure 6)

	PARAMI	TER	TEST CONDITIONS	MIN	TYP <sup>‡</sup>	MAX	UNIT
Ц	Input leakage current	FORCEOFF, FORCEON			±0.01	±1	μΑ
		Auto-powerdown plus disabled	No load, FORCEOFF and FORCEON at V <sub>CC</sub>		0.5	2	mA
Icc	Supply current	Powered off	No load, FORCEOFF at GND		1	10	
.00	$C = (T_A = 25^{\circ}C)$	Auto-powerdown plus enabled	No load, FORCEOFF at V <sub>CC</sub> , FORCEON at GND, All RIN are open or grounded		1	10	μΑ

<sup>‡</sup> All typical values are at  $V_{CC} = 3.3 \text{ V}$  or  $V_{CC} = 5 \text{ V}$ , and  $T_A = 25^{\circ}\text{C}$ .

NOTE 4: Testing supply conditions are C1–C4 = 0.1  $\mu$ F at V<sub>CC</sub> = 3.3 V ± 0.15 V; C1–C4 = 0.22  $\mu$ F at V<sub>CC</sub> = 3.3 V ± 0.3 V; and C1 = 0.047  $\mu$ F and C2–C4 = 0.33  $\mu$ F at V<sub>CC</sub> = 5 V  $\pm$  0.5 V.



#### **DRIVER SECTION**

## electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 4 and Figure 6)

	PARAMETER	TES	ST CONDITIONS		MIN	TYP	MAX	UNIT
Vон	High-level output voltage	All DOUT at R <sub>L</sub> = $3 \text{ k}\Omega$ to	All DOUT at R <sub>L</sub> = 3 k $\Omega$ to GND		5	5.4		V
VOL	Low-level output voltage	III DOUT at R <sub>L</sub> = 3 k $\Omega$ to GND		-5	-5.4		V	
ΙΗ	High-level input current	VI = VCC				±0.01	±1	μΑ
Iμ	Low-level input current	V <sub>I</sub> at GND				±0.01	±1	μΑ
	Object already autout access of	V <sub>CC</sub> = 3.6 V,	V <sub>O</sub> = 0 V			±35	±60	A
los	Short-circuit output current‡	V <sub>CC</sub> = 5.5 V,	V <sub>O</sub> = 0 V			±40	±100	mA
r <sub>O</sub>	Output resistance	$V_{CC}$ , V+, and V- = 0 V,	V <sub>O</sub> = ±2 V		300	10M	·	Ω
l <sub>off</sub>	Output leakage current	FORCEOFF = GND,	$V_0 = \pm 12 V$ ,	$V_{CC} = 0 \text{ to } 5.5 \text{ V}$			±25	μΑ

<sup>&</sup>lt;sup>†</sup> All typical values are at  $V_{CC}$  = 3.3 V or  $V_{CC}$  = 5 V, and  $T_A$  = 25°C.

NOTE 4: Testing supply conditions are C1–C4 = 0.1  $\mu$ F at V<sub>CC</sub> = 3.3 V  $\pm$  0.15 V; C1–C4 = 0.22  $\mu$ F at V<sub>CC</sub> = 3.3 V  $\pm$  0.3 V; and C1 = 0.047  $\mu$ F and C2–C4 = 0.33  $\mu F$  at V<sub>CC</sub> = 5 V  $\pm$  0.5 V.

## switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 4 and Figure 6)

	PARAMETER	TEST CONDITIONS		MIN	TYP <sup>†</sup>	MAX	UNIT
	Maximum data rate	C <sub>L</sub> = 1000 pF, One DOUT switching,	$R_L = 3 k\Omega$ , See Figure 1	150	250		kbit/s
tsk(p)	Pulse skew§	C <sub>L</sub> = 150 pF to 2500 pF	$R_L$ = 3 kΩ to 7 kΩ, See Figure 2		100		ns
SR(tr)	Slew rate, transition region	V <sub>CC</sub> = 3.3 V,	C <sub>L</sub> = 150 pF to 1000 pF	6		30	V/μs
SK(II)	(see Figure 1)	$R_L = 3 \text{ k}\Omega \text{ to } 7 \text{ k}\Omega$	C <sub>L</sub> = 150 pF to 2500 pF	4		30	ν/μ5

<sup>&</sup>lt;sup>†</sup> All typical values are at  $V_{CC} = 3.3 \text{ V}$  or  $V_{CC} = 5 \text{ V}$ , and  $T_A = 25^{\circ}\text{C}$ .



<sup>\$</sup> Short-circuit durations should be controlled to prevent exceeding the device absolute power-dissipation ratings, and not more than one output should be shorted at a time.

<sup>§</sup> Pulse skew is defined as |tplh - tphl| of each channel of the same device.

NOTE 4: Testing supply conditions are C1–C4 = 0.1  $\mu$ F at V $_{CC}$  = 3.3 V  $\pm$  0.15 V; C1–C4 = 0.22  $\mu$ F at V $_{CC}$  = 3.3 V  $\pm$  0.3 V; and C1 = 0.047  $\mu$ F and C2–C4 = 0.33  $\mu F$  at V<sub>CC</sub> = 5 V  $\pm$  0.5 V.

#### RECEIVER SECTION

## electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 4 and Figure 6)

	PARAMETER	TEST CONDITIONS	MIN	TYP <sup>†</sup>	MAX	UNIT	
Vон	High-level output voltage	$I_{OH} = -1 \text{ mA}$	V <sub>CC</sub> – 0.6 V	V <sub>CC</sub> – 0.1 V		V	
VOL	Low-level output voltage	I <sub>OL</sub> = 1.6 mA			0.4	V	
\/-	Desitive main a input three held veltage	V <sub>CC</sub> = 3.3 V		1.5	2.4		
V <sub>IT+</sub>	Positive-going input threshold voltage	V <sub>CC</sub> = 5 V		1.8	2.4	V	
.,	No and the material through all the life and	V <sub>CC</sub> = 3.3 V	0.6	1.2		.,	
V <sub>IT</sub> _	Negative-going input threshold voltage	V <sub>CC</sub> = 5 V	0.8	1.5		V	
V <sub>hys</sub>	Input hysteresis (V <sub>IT+</sub> - V <sub>IT-</sub> )			0.3		V	
l <sub>off</sub>	Output leakage current (except ROUT1B)	FORCEOFF = 0 V		±0.05	±10	μΑ	
rį	Input resistance	$V_I = \pm 3 \text{ V to } \pm 25 \text{ V}$	3	5	7	kΩ	

<sup>&</sup>lt;sup>†</sup> All typical values are at  $V_{CC} = 3.3 \text{ V}$  or  $V_{CC} = 5 \text{ V}$ , and  $T_A = 25^{\circ}\text{C}$ .

NOTE 4: Testing supply conditions are C1–C4 = 0.1  $\mu$ F at V<sub>CC</sub> = 3.3 V ± 0.15 V; C1–C4 = 0.22  $\mu$ F at V<sub>CC</sub> = 3.3 V ± 0.3 V; and C1 = 0.047  $\mu$ F and C2–C4 = 0.33  $\mu$ F at V<sub>CC</sub> = 5 V  $\pm$  0.5 V.

### switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 4)

	PARAMETER	TEST CONDITIONS	MIN .	TYP	MAX	UNIT
t <sub>PLH</sub>	Propagation delay time, low- to high-level output	0 450 5 0 5 5 7 7 9		150		ns
tPHL	Propagation delay time, high- to low-level output	C <sub>L</sub> = 150 pF, See Figure 3		150		ns
t <sub>en</sub>	Output enable time	0 450 5 B 010 0 5 5 5 5 5 5		200		ns
tdis	Output disable time	$C_L = 150 \text{ pF}, R_L = 3 \text{ k}\Omega, \text{See Figure 4}$		200		ns
tsk(p)	Pulse skew <sup>‡</sup>	See Figure 3	_	50		ns

<sup>&</sup>lt;sup>†</sup> All typical values are at  $V_{CC} = 3.3 \text{ V}$  or  $V_{CC} = 5 \text{ V}$ , and  $T_A = 25^{\circ}C$ .

NOTE 4: Testing supply conditions are C1–C4 = 0.1  $\mu$ F at V<sub>CC</sub> = 3.3 V  $\pm$  0.15 V; C1–C4 = 0.22  $\mu$ F at V<sub>CC</sub> = 3.3 V  $\pm$  0.3 V; and C1 = 0.047  $\mu$ F and C2–C4 = 0.33  $\mu$ F at V<sub>CC</sub> = 5 V  $\pm$  0.5 V.



 $<sup>\</sup>ddagger$  Pulse skew is defined as  $|t_{PLH} - t_{PHL}|$  of each channel of the same device.

#### **AUTO-POWERDOWN PLUS SECTION**

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 5)

	PARAMETER	TEST CONDITIONS	MIN	TYP <sup>†</sup>	MAX	UNIT
VT+(valid)	Receiver input threshold for INVALID high-level output voltage	FORCEON = GND, FORCEOFF = V <sub>CC</sub>			2.7	V
V <sub>T</sub> -(valid)	Receiver input threshold for INVALID high-level output voltage	FORCEON = GND, FORCEOFF = V <sub>CC</sub>	-2.7			٧
VT(invalid)	Receiver input threshold for INVALID low-level output voltage	FORCEON = GND, FORCEOFF = V <sub>CC</sub>	-0.3		0.3	٧
VOH	INVALID high-level output voltage	I <sub>OH</sub> = -1 mA, FORCEON = GND, FORCEOFF = V <sub>CC</sub>	V <sub>CC</sub> – 0.6			V
VOL	INVALID low-level output voltage	$I_{OL} = 1.6 \text{ mA}$ , FORCEON = GND, FORCEOFF = $V_{CC}$			0.4	٧

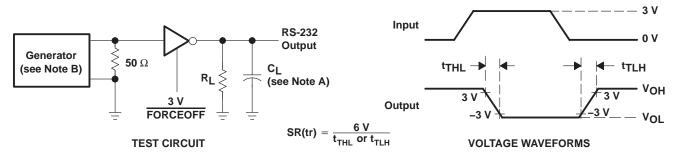
<sup>&</sup>lt;sup>†</sup> All typical values are at  $V_{CC} = 3.3 \text{ V}$  or  $V_{CC} = 5 \text{ V}$ , and  $T_A = 25^{\circ}\text{C}$ .

## switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 5)

	PARAMETER	MIN	TYP <sup>†</sup>	MAX	UNIT
<sup>t</sup> valid	Propagation delay time, low- to high-level output		0.1		μs
<sup>t</sup> invalid	Propagation delay time, high- to low-level output		50		μs
ten	Supply enable time		25		μs
<sup>t</sup> dis	Receiver or driver edge to auto-powerdown plus	15	30	60	S

<sup>&</sup>lt;sup>†</sup> All typical values are at  $V_{CC} = 3.3 \text{ V}$  or  $V_{CC} = 5 \text{ V}$ , and  $T_A = 25^{\circ}\text{C}$ .

### PARAMETER MEASUREMENT INFORMATION



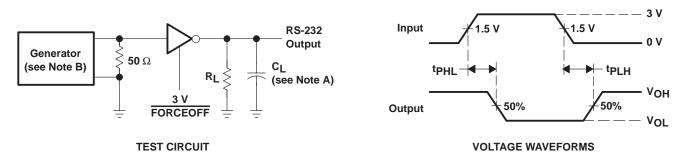
NOTES: A. C<sub>L</sub> includes probe and jig capacitance.

B. The pulse generator has the following characteristics: PRR = 250 kbit/s,  $Z_O = 50 \Omega$ , 50% duty cycle,  $t_f \le 10$  ns.  $t_f \le 10$  ns.

Figure 1. Driver Slew Rate



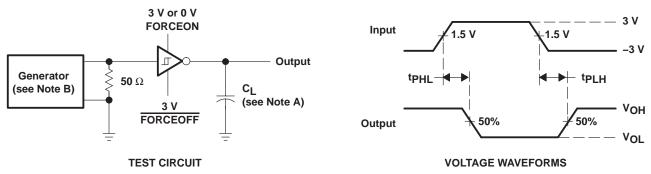
#### PARAMETER MEASUREMENT INFORMATION



NOTES: A. C<sub>I</sub> includes probe and jig capacitance.

B. The pulse generator has the following characteristics: PRR = 250 kbit/s,  $Z_O = 50 \Omega$ , 50% duty cycle,  $t_r \le 10$  ns,  $t_f \le 10$  ns.

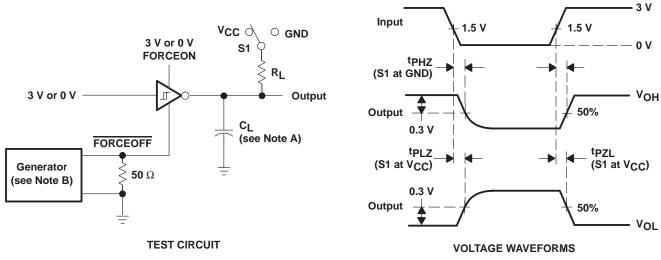
Figure 2. Driver Pulse Skew



NOTES: A. C<sub>L</sub> includes probe and jig capacitance.

B. The pulse generator has the following characteristics:  $Z_O = 50 \Omega$ , 50% duty cycle,  $t_\Gamma \le 10$  ns,  $t_f \le 10$  ns.

Figure 3. Receiver Propagation Delay Times



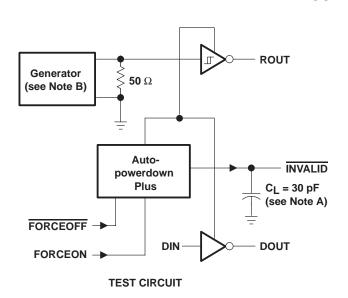
NOTES: A.  $C_L$  includes probe and jig capacitance.

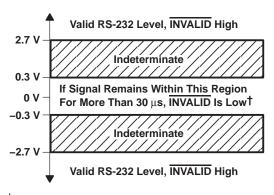
- B. The pulse generator has the following characteristics:  $Z_Q = 50 \Omega$ , 50% duty cycle,  $t_f \le 10$  ns,  $t_f \le 10$  ns.
- C. tpLz and tpHz are the same as tdis.
- D. tpzL and tpzH are the same as ten.

Figure 4. Receiver Enable and Disable Times



#### PARAMETER MEASUREMENT INFORMATION





† Auto-powerdown plus disables drivers and reduces supply current to 1  $\mu$ A.

- NOTES: A. C<sub>L</sub> includes probe and jig capacitance.
  - B. The pulse generator has the following characteristics: PRR = 5 kbit/s,  $Z_{O}$  = 50  $\Omega$ , 50% duty cycle,  $t_f \le 10$  ns,  $t_f \le 10$  ns.

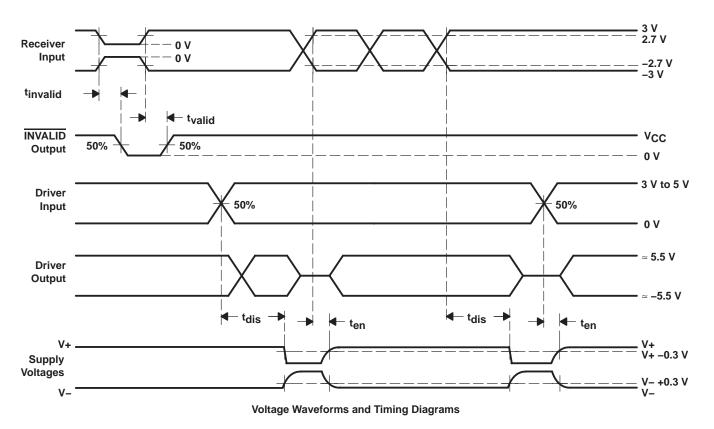
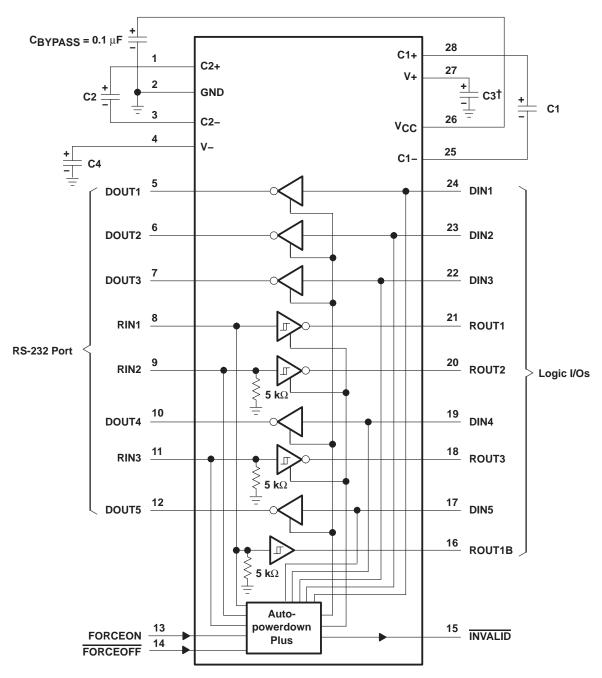


Figure 5. INVALID Propagation-Delay Times and Supply-Enabling Time



### **APPLICATION INFORMATION**



†C3 can be connected to VCC or GND.

NOTE A: Resistor values shown are nominal.

V<sub>CC</sub> vs CAPACITOR VALUES

VCC	C1	C2, C3, and C4			
	0.1 μF 0.22 μF 0.047 μF 0.22 μF	0.1 μF 0.22 μF 0.33 μF 1 μF			

Figure 6. Typical Operating Circuit and Capacitor Values



www.ti.com 1-May-2025

#### PACKAGING INFORMATION

Orderable part number	Status (1)	Material type	Package   Pins	Package qty   Carrier	RoHS	Lead finish/ Ball material	MSL rating/ Peak reflow	Op temp (°C)	Part marking (6)
MAX3238IPWG4Q1	Active	Production	TSSOP (PW)   28	50   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	MB3238Q
MAX3238IPWQ1	Active	Production	TSSOP (PW)   28	50   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	MB3238Q
MAX3238IPWRG4Q1	Active	Production	TSSOP (PW)   28	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	MB3238Q

<sup>(1)</sup> Status: For more details on status, see our product life cycle.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

**Important Information and Disclaimer:** The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

#### OTHER QUALIFIED VERSIONS OF MAX3238-Q1:

Catalog: MAX3238

<sup>(2)</sup> Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

<sup>(3)</sup> RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

<sup>(4)</sup> Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

<sup>(5)</sup> MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

<sup>(6)</sup> Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.



# **PACKAGE OPTION ADDENDUM**

www.ti.com 1-May-2025

NOTE: Qualified Version Definitions:

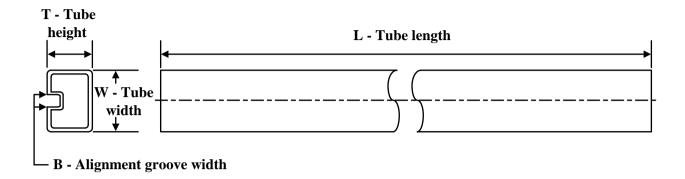
• Catalog - TI's standard catalog product





www.ti.com 20-Apr-2024

## **TUBE**

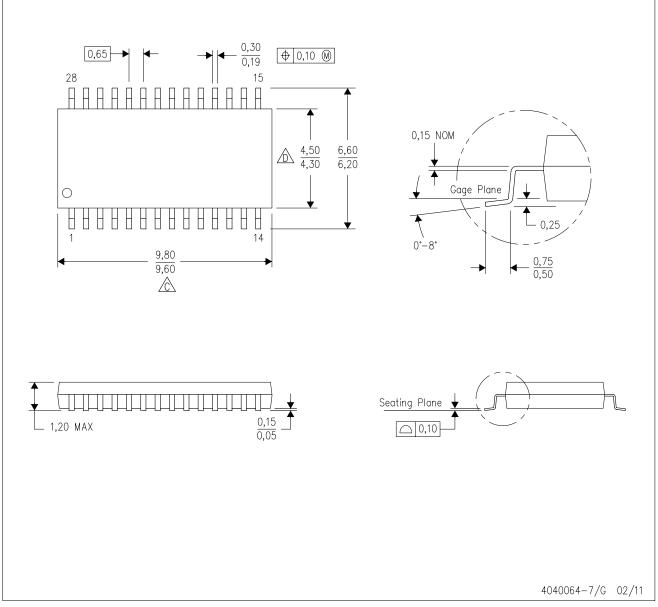


### \*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
MAX3238IPWG4Q1	PW	TSSOP	28	50	530	10.2	3600	3.5
MAX3238IPWQ1	PW	TSSOP	28	50	530	10.2	3600	3.5

PW (R-PDSO-G28)

## PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M—1994.
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
- E. Falls within JEDEC MO-153



### IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATA SHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, regulatory or other requirements.

These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to TI's Terms of Sale or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products.

TI objects to and rejects any additional or different terms you may have proposed.

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265 Copyright © 2025. Texas Instruments Incorporated